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IMPORTANT NOTICE

10 December 2015

1. Global joint venture starts operations as WeEn Semiconductors

Dear customer,

As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

In this document where the previous NXP references remain, please use the new links as shown below.

WWW - For www.nxp.com use www.ween-semi.com
Email - For salesaddresses@nxp.com use salesaddresses@ween-semi.com

For the copyright notice at the bottom of each page (or elsewhere in the document, depending on the version) "© **NXP Semiconductors N.V. *{year}*. All rights reserved**" becomes "© **WeEn Semiconductors Co., Ltd. *{year}*. All rights reserved**"

If you have any questions related to this document, please contact our nearest sales office via e-mail or phone (details via salesaddresses@ween-semi.com).

Thank you for your cooperation and understanding,

WeEn Semiconductors

founded by NXP

DATA SHEET

BYR29 series
Rectifier diodes
ultrafast

Product specification

September 1998

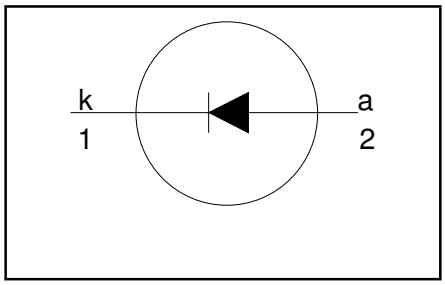
Rectifier diodes ultrafast

BYR29 series

FEATURES

- Low forward volt drop
- Fast switching
- Soft recovery characteristic
- Reverse surge capability
- High thermal cycling performance
- Low thermal resistance

SYMBOL



QUICK REFERENCE DATA

V_R = 500 V/ 600 V/ 700 V / 800 V

$V_F \leq 1.5$ V

$I_{F(AV)}$ = 8 A

$t_{rr} \leq 75$ ns

GENERAL DESCRIPTION

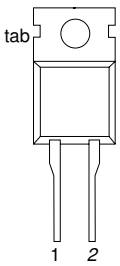
Ultra-fast, epitaxial rectifier diodes intended for use as output rectifiers in high frequency switched mode power supplies.

The BYR29 series is supplied in the conventional leaded SOD59 (TO220AC) package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode
tab	cathode

SOD59 (TO220AC)



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.				UNIT
		BYR29		**-500**	**-600**	**-700**	**-800**	
V_{RRM}	Peak repetitive reverse voltage		-	500	600	700	800	V
V_{RWM}	Crest working reverse voltage		-	500	600	700	800	V
V_R	Continuous reverse voltage		-	500	600	700	800	V
$I_{F(AV)}$	Average forward current[1]	square wave; $\delta = 0.5$; $T_{mb} \leq 115$ ˚C	-	8				A
I_{FRM}	Repetitive peak forward current	t = 25 µs; $\delta = 0.5$; $T_{mb} \leq 115$ ˚C	-	16				A
I_{FSM}	Non-repetitive peak forward current	t = 10 ms	-	60				A
		t = 8.3 ms sinusoidal; with reapplied $V_{RRM(max)}$	-	66				A
T_{stg}	Storage temperature		-40	150				˚C
T_j	Operating junction temperature		-	150				˚C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j\text{-}mb}$	Thermal resistance junction to mounting base		-	-	2.5	K/W
$R_{th\ j\text{-}a}$	Thermal resistance junction to ambient	in free air.	-	60	-	K/W

1 Neglecting switching and reverse current losses

ELECTRICAL CHARACTERISTICS

T_j = 25 ˚C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_F	Forward voltage	I_F = 8 A; T_j = 150˚C	-	1.07	1.50	V
		I_F = 20 A	-	1.75	1.95	V
I_R	Reverse current	$V_R = V_{RRM}$	-	1.0	10	µA
		$V_R = V_{RRM}$; T_j = 100 ˚C	-	0.1	0.2	mA
Q_s	Reverse recovery charge	I_F = 2 A to $V_R \geq$ 30 V; dI_F/dt = 20 A/µs	-	150	200	nC
t_{rr}	Reverse recovery time	I_F = 1 A to $V_R \geq$ 30 V; dI_F/dt = 100 A/µs	-	60	75	ns
I_{rrm}	Peak reverse recovery current	I_F = 10 A to $V_R \geq$ 30 V; dI_F/dt = 50 A/µs; T_j = 100 ˚C	-	-	6	A
V_{fr}	Forward recovery voltage	I_F = 10 A; dI_F/dt = 10 A/µs	-	5.0	-	V

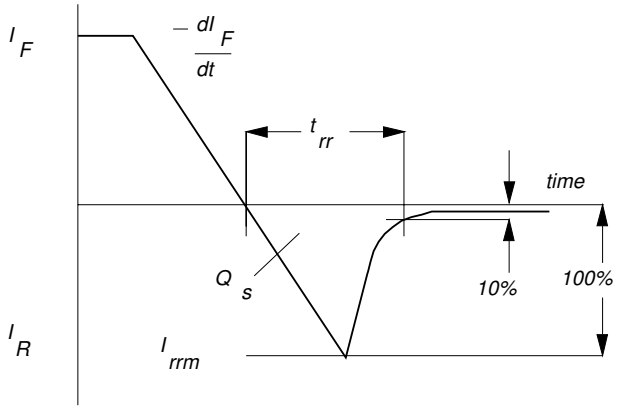


Fig.1. Definition of t_{rr}, Q_s and I_{rrm}

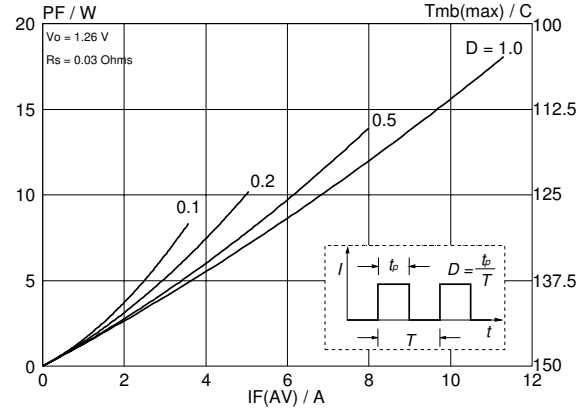


Fig.3. Maximum forward dissipation $P_F = f(I_{F(AV)})$; square wave where $I_{F(AV)} = I_{F(RMS)} \times \sqrt{D}$.

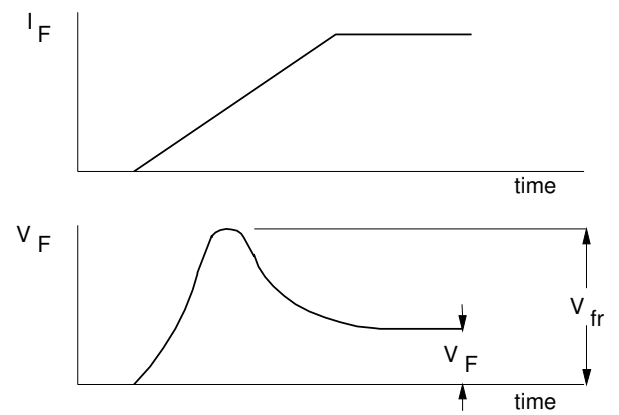


Fig.2. Definition of V_{fr}

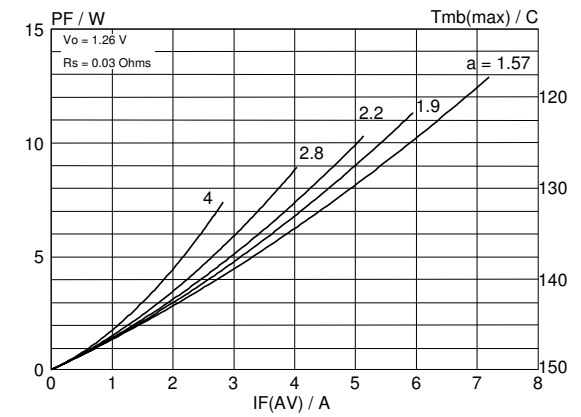


Fig.4. Maximum forward dissipation $P_F = f(I_{F(AV)})$; sinusoidal current waveform where a = form factor = $I_{F(RMS)} / I_{F(AV)}$.

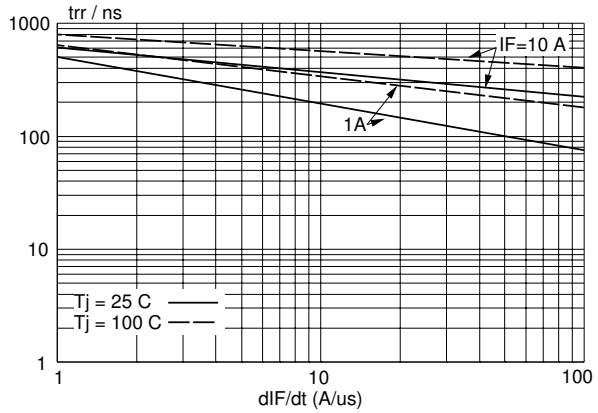


Fig.5. Maximum t_{rr} at T_j = 25˚C and 100˚C.

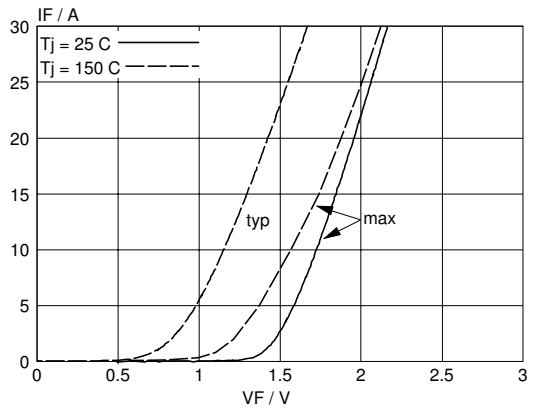


Fig.7. Typical and maximum forward characteristic $I_F = f(V_F)$; parameter T_j

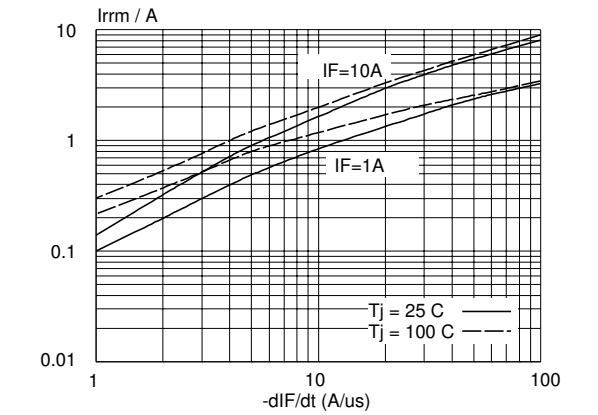


Fig.6. Maximum I_{rrm} at T_j = 25˚C and 100˚C.

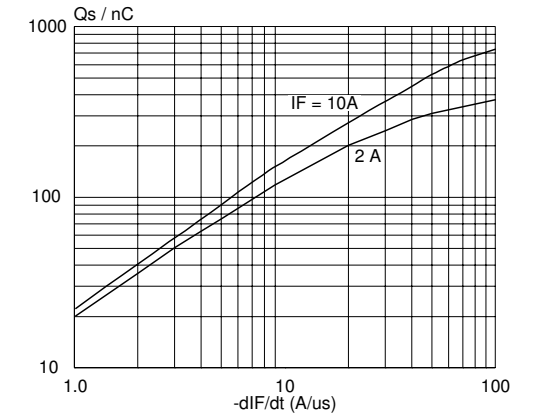


Fig.8. Maximum Q_s at T_j = 25˚C

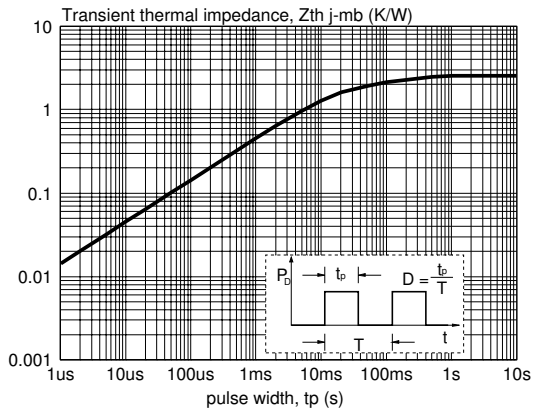


Fig.9. Transient thermal impedance $Z_{th} = f(t_p)$

MECHANICAL DATA

Dimensions in mm

Net Mass: 2 g

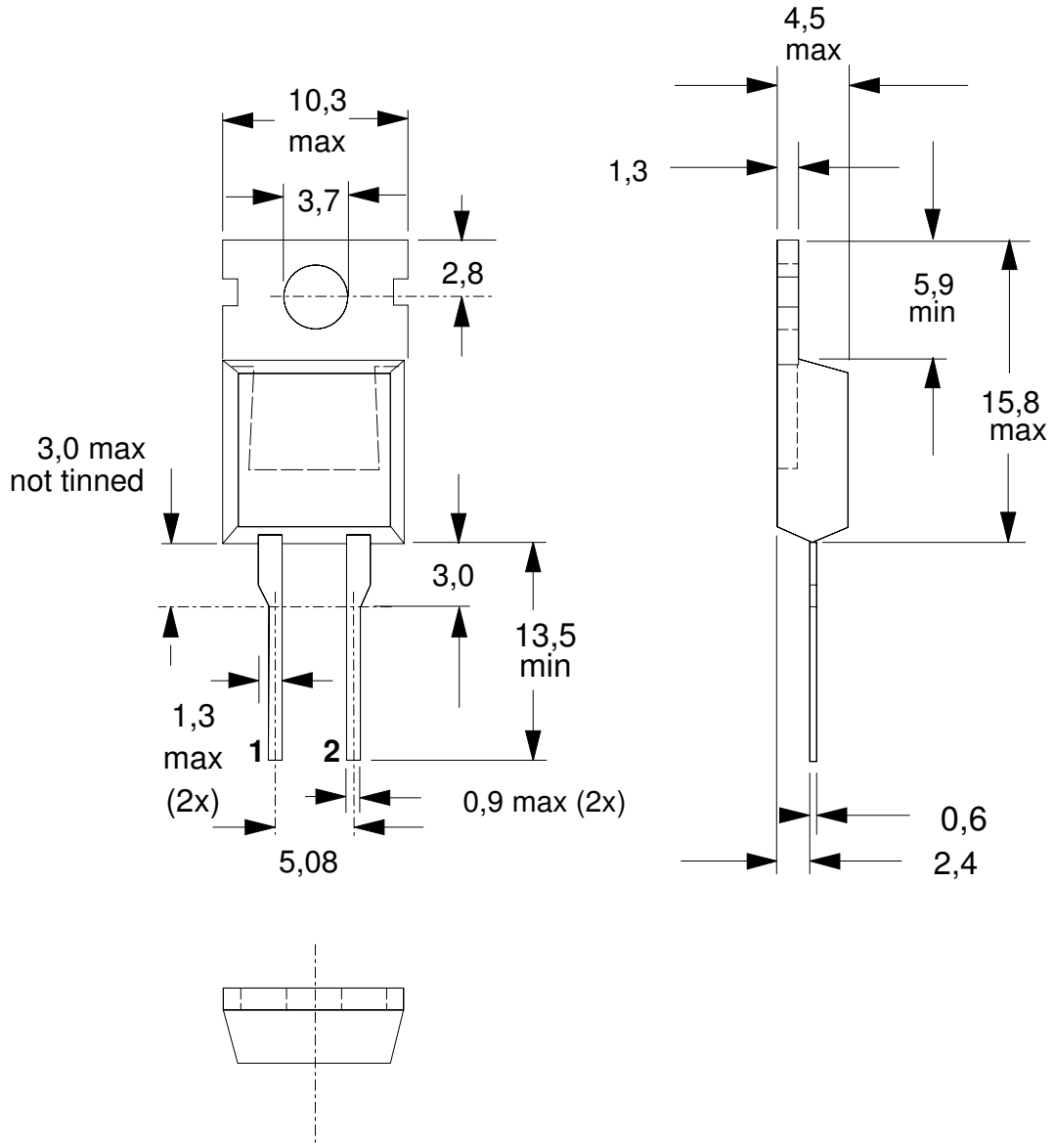


Fig.10. SOD59 (TO220AC). pin 1 connected to mounting base.

Notes
1. Refer to mounting instructions for TO220 envelopes.
2. Epoxy meets UL94 V0 at 1/8".

Legal information

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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